

# HCS06FF120E0C1

## 1200V/6.2mΩ Half Bridge SiC MOSFET Module

### Description

The HCS06FF120E0C1 is a half bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips designed for the applications such as Solar Inverter Systems, Fuel cell-DC/DC converter, Uninterruptible Power Supplier, Energy Storage Systems.



### Features

- Blocking voltage:1200V
- $R_{ds(on)}$ :6.2mΩ @25°C;10.3mΩ @175°C
- Low Switching Losses
- 175°C maximum junction temperature
- Si<sub>3</sub>N<sub>4</sub>AMB
- Thermistor inside

### Applications

- Solar inverterSystems
- Fuel cell-DC/DC converter
- Uninterruptible Power Supplier
- Energy Storage Systems
- Solid State Relay

### Circuit diagram

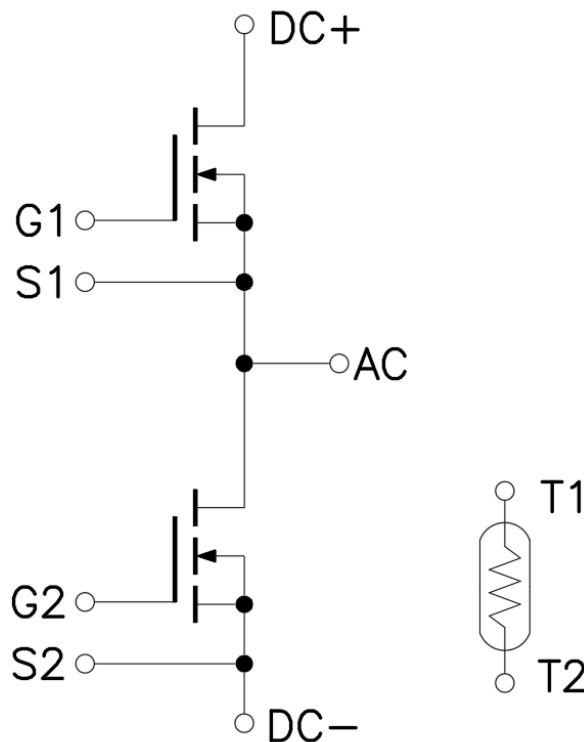


Figure 1. Out drawing & circuit diagram for HCS06FF120E0C1

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## Pin Configuration and Marking Information

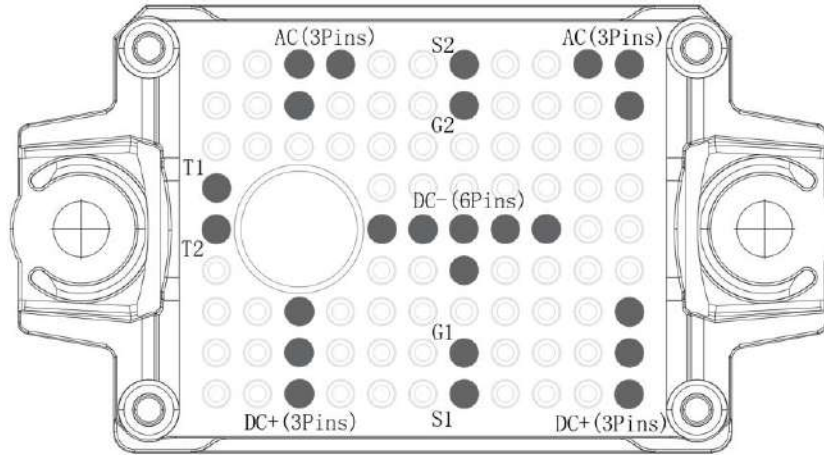


Figure 2. Pin configuration

Symbol	Description
AC	Output terminal of half bridge
S2	Low side source signal terminal
G2	Low side gate signal terminal
DC+	DC+ Bus connection
DC-	DC- Bus connection
S1	High side source signal terminal
G1	High side gate signal terminal
T1	Thermistor connection 1
T2	Thermistor connection 2

## Module

Parameter	Condition	Value	Unit
Isolation voltage	RMS, f =50Hz, t =1min	3.4	kV
Clearance	Terminal to Terminal	5	mm
	Terminal to Heatsink	10	mm
Creepage distance	Terminal to Terminal	6.3	mm
	Terminal to Heatsink	12.7	mm
Comparative Tracking Index	-	600	-
Weight	-	26	g

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### Maximum Ratings ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Condition	Ratings	Unit
$V_{DSS}$	Drain-Source Voltage	G-S Short	1200	V
$V_{GSS}$	Gate-Source Voltage	D-S Short, Note1	-10 to 22	V
$I_{DS}$	DC Continuous Drain Current	$T_f = 95^\circ\text{C}$ , Note2	150	A
$I_{SD}$	Source (Body diode) Current	$T_f = 95^\circ\text{C}$ , with ON signal	150	A
$I_{DP}$	Drain Pulse Current, Peak	Less than 1ms, Note3	300	A
$T_{jop}$	Operation junction temperature	-	-40 to 175	$^\circ\text{C}$
$T_{stg}$	Storage temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Recommended Operating Value, +18V/-5V, +18V/-4V, +15V/-4V.

Note2: Case temperature( $T_c$ ) is defined on the surface of base plate just under the chips.

Note3: Pulse width limited by maximum junction temperature

### NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
$R_{25}$	Resistance	$T_c = 25^\circ\text{C}$	-	5	-	kΩ
R/R	Deviation of $R_{100}$	$T_c = 100^\circ\text{C}$ , $R_{100} = 493 \Omega$	-5	-	5	%
$P_{25}$	Power dissipation	$T_c = 25^\circ\text{C}$	-	-	20	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

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## 1200V/6.2mΩ Half Bridge SiC MOSFET Module

### MOSFET Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=200\mu A$	1200	-	-	V	
$I_{DSS}$	Zero gate voltage drain current	$V_{DS}=1200V, V_{GS}=0V$	-	5	-	$\mu A$	
$V_{GS(th)}$	Gate-source threshold voltage	$I_D=40mA, V_{DS}=V_{GS}$	2.1	2.7	-	V	
$I_{GSS+}$	Gate-Source Leakage Current	$V_{GS}=22V, V_{DS}=0V, T_j=25^\circ C$	-	-	200	nA	
$I_{GSS-}$		$V_{GS}=-10V, V_{DS}=0V, T_j=25^\circ C$	-	-	-200	nA	
$R_{DS(on)}$ (Chip)	Static drain-source On-state resistance	$I_D=150A$ $V_{GS}=+18V$	$T_j=25^\circ C$	-	6.2	-	mΩ
			$T_j=175^\circ C$	-	10.3	-	mΩ
$V_{DS(on)}$ (Chip)	Static drain-source On-state voltage	$I_D=150A$ $V_{GS}=+18V$	$T_j=25^\circ C$	-	0.93	-	V
			$T_j=175^\circ C$	-	1.55	-	V
$C_{iss}$	Input capacitance	$V_D=800V, V_{GS}=0V, f=100kHz,$ $V_{AC}=25mV$	-	14.4	-	nF	
$C_{oss}$	Output capacitance		-	0.4	-	nF	
$C_{rss}$	Reverse transfer capacitance		-	0.03	-	nF	
$Q_G$	Total gate charge	$V_{DS}=800V, I_D=150A, V_{GS}=+18/-5V$	-	400	-	nC	
$R_{Gint}$	Internal Gate Resistance	$T_j=25^\circ C$	-	0.25	-	Ω	
$t_{d(on)}$	Turn-on delay time	$V_{DD}=600V$ $I_D=150A$ $V_{GS}=+18/-4V$ $R_G=3.3\Omega$ Inductive load switching operation	$T_j=25^\circ C$	-	48	-	ns
			$T_j=150^\circ C$	-	45	-	
$t_r$	Rise time		$T_j=25^\circ C$	-	32	-	ns
			$T_j=150^\circ C$	-	30	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ C$	-	39	-	ns
			$T_j=150^\circ C$	-	45	-	
$t_f$	Fall time		$T_j=25^\circ C$	-	22	-	ns
			$T_j=150^\circ C$	-	26	-	
$E_{on}$	Turn-on power dissipation		$T_j=25^\circ C$	-	1.52	-	mJ
			$T_j=150^\circ C$	-	1.99	-	
$E_{off}$	Turn-off power dissipation		$T_j=25^\circ C$	-	0.93	-	mJ
			$T_j=150^\circ C$	-	1.12	-	
$R_{th(j-e)}$	FET Thermal Resistance	Junction to Case/MOSFET	-	0.12	-	K/W	
$R_{th(c-f)}$	Contact thermal resistance	With thermal conductive grease/MOSFET	-	0.15	-	K/W	

Assumes Thermal Conductivity of grease is 2.8 W/m · K and thickness is 50um.

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### Body Diode Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip: Target)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max.		
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = -5\text{V}$ $I_{SD} = 150\text{A}$	$T_j = 25^\circ\text{C}$	-	5.0	-	V
			$T_j = 150^\circ\text{C}$	-	4.5	-	
$T_{rr}$	Reverse recovery time	$V_{DD} = 600\text{V}$ $I_D = 150\text{A}$	$T_j = 25^\circ\text{C}$	-	41	-	ns
			$T_j = 150^\circ\text{C}$	-	45	-	
$Q_{rr}$	Reverse recovery charge	$V_{GS} = +18/-4\text{V}$ $R_G = 3.3\ \Omega$	$T_j = 25^\circ\text{C}$	-	1.05	-	$\mu\text{C}$
			$T_j = 150^\circ\text{C}$	-	1.93	-	

### Test Conditions

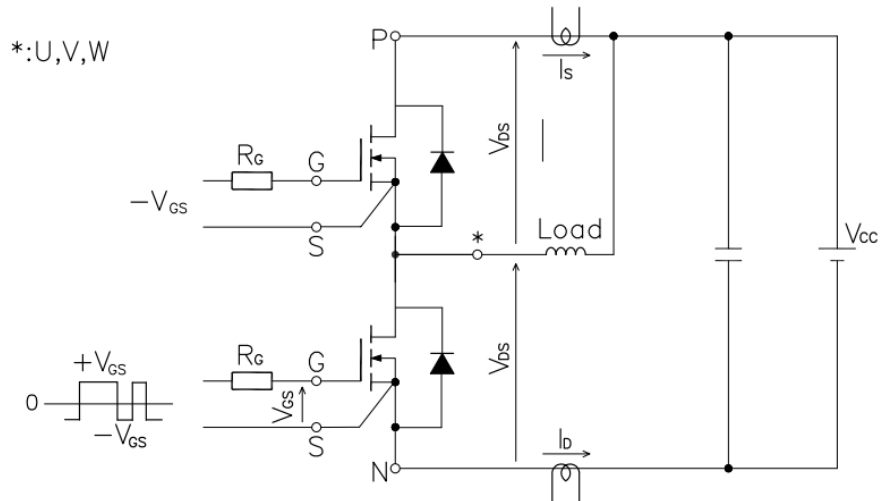


Figure 3. Switching time measure circuit

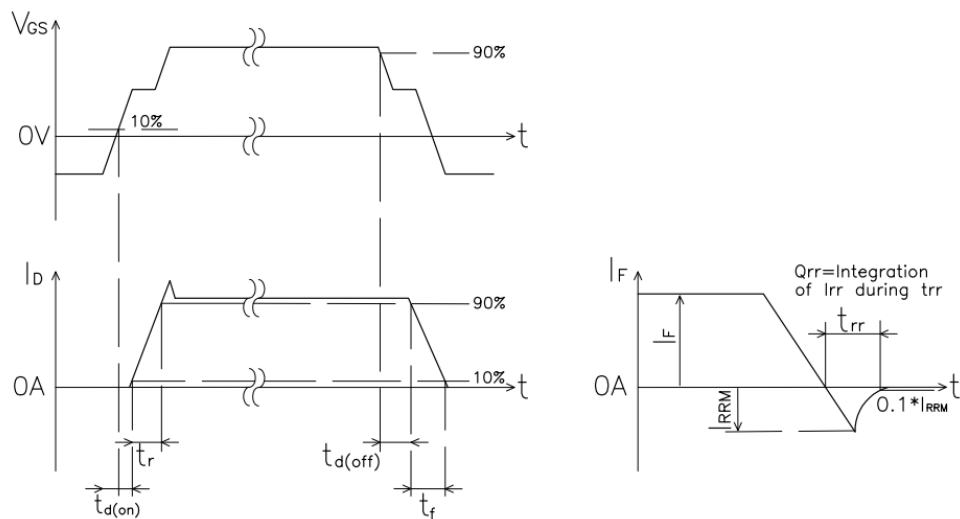


Figure 4. Switching time definition

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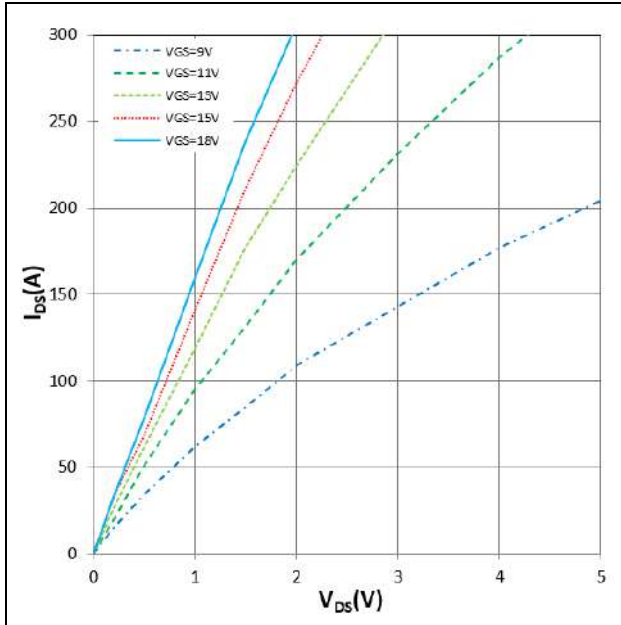


Figure 5.  $I_{DS}$  vs  $V_{DS}$   
 $T_j = 25^\circ\text{C}$ ,  $V_{GS}$  parameter

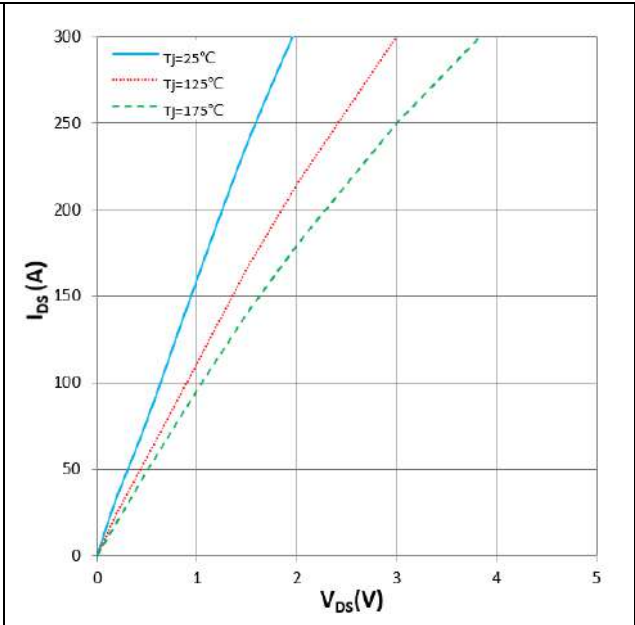


Figure 6.  $I_{DS}$  vs  $V_{DS}$   
 $V_{GS} = +18\text{V}$

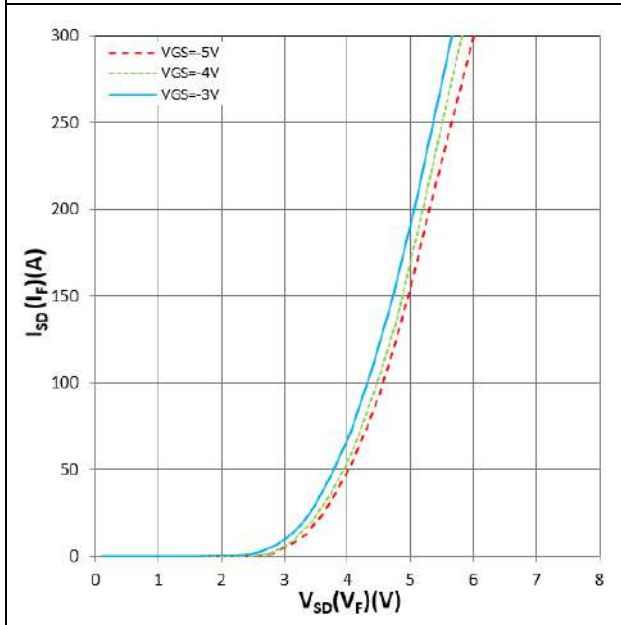


Figure 7.  $I_{SD}$  vs  $V_{SD} (V_F)$   
 $T_j = 25^\circ\text{C}$ ,  $V_{GS}$  parameter

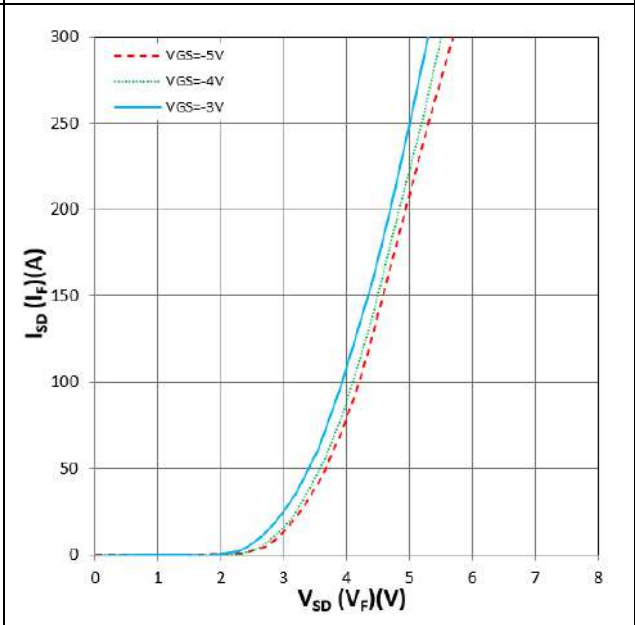


Figure 8.  $I_{SD}$  vs  $V_{SD} (V_F)$   
 $T_j = 150^\circ\text{C}$ ,  $V_{GS}$  parameter

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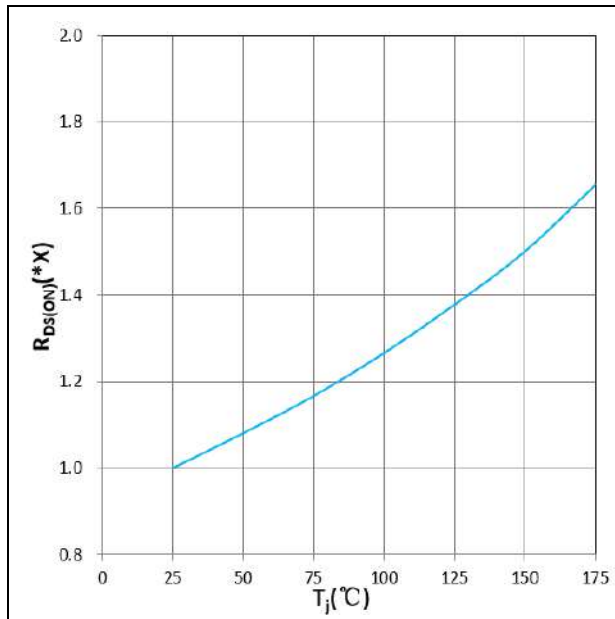


Figure 9.  $R_{DS(ON)}$  vs  $T_j$   
 $V_{GS} = +18V$ ,  $I_D = 150A$ ,  $1.0X = 6.2m\Omega$

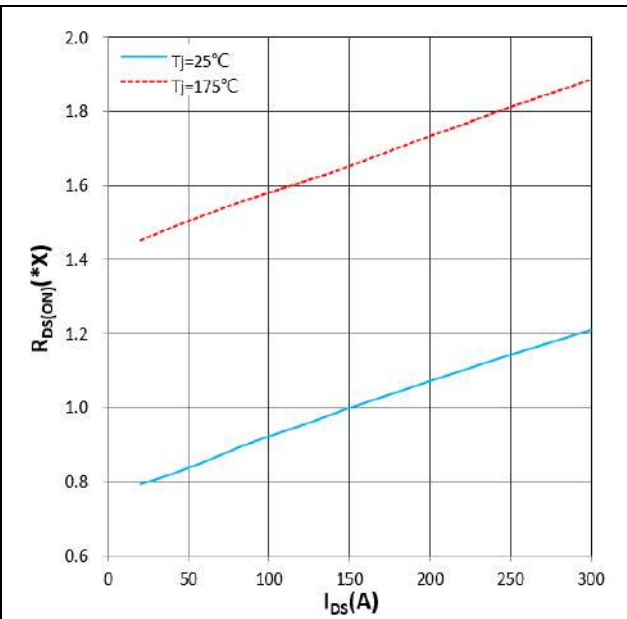


Figure 10.  $R_{DS(ON)}$  vs  $I_{DS}$   
 $V_{GS} = +18V$ ,  $I_D = 150A$ ,  $1.0X = 6.2m\Omega$

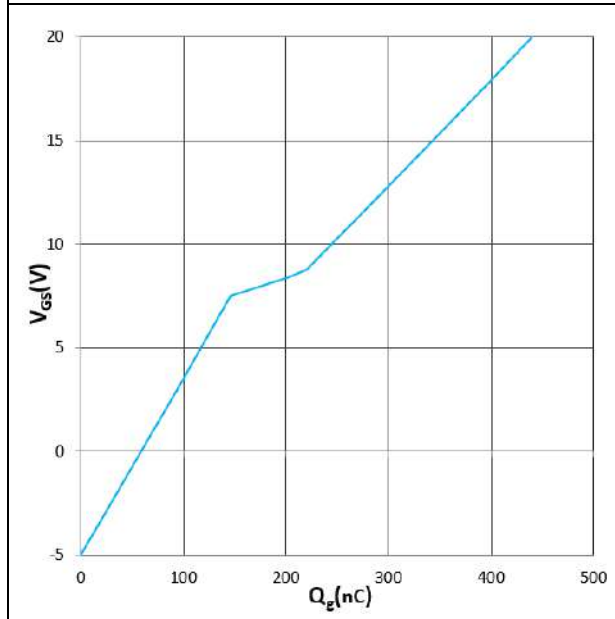


Figure 11.  $V_{GS}$  vs  $Q_g$   
 $V_{DS} = 800V$ ,  $I_D = 150A$ ,  $T_j = 25^\circ C$

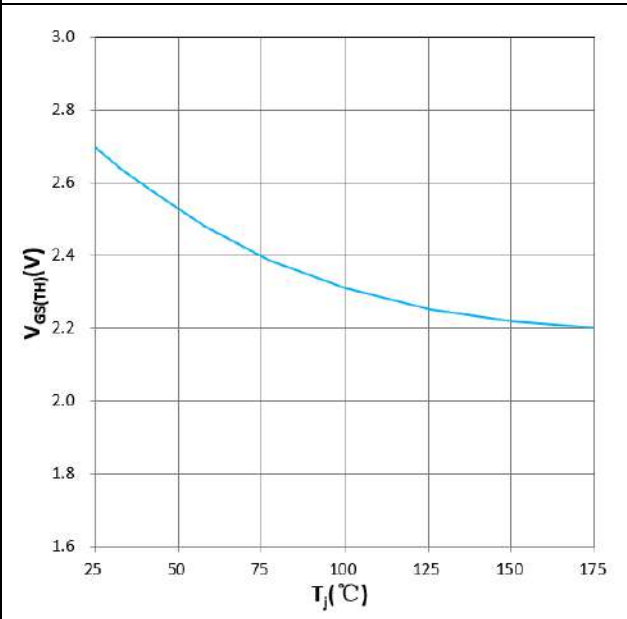


Figure 12.  $V_{GS(TH)}$  vs  $T_j$   
 $V_{GS} = V_{DS}$ ,  $I_D = 40mA$

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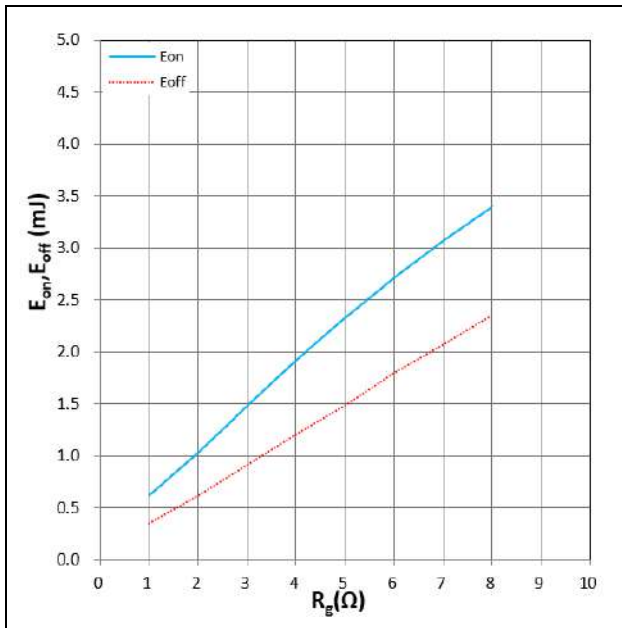


Figure 13.  $E_{on}$ ,  $E_{off}$  vs  $R_G$   
 $T_j = 25^\circ\text{C}$ ,  $I_D = 150\text{A}$ ,  $V_{GS} = +18\text{V}/-4\text{V}$

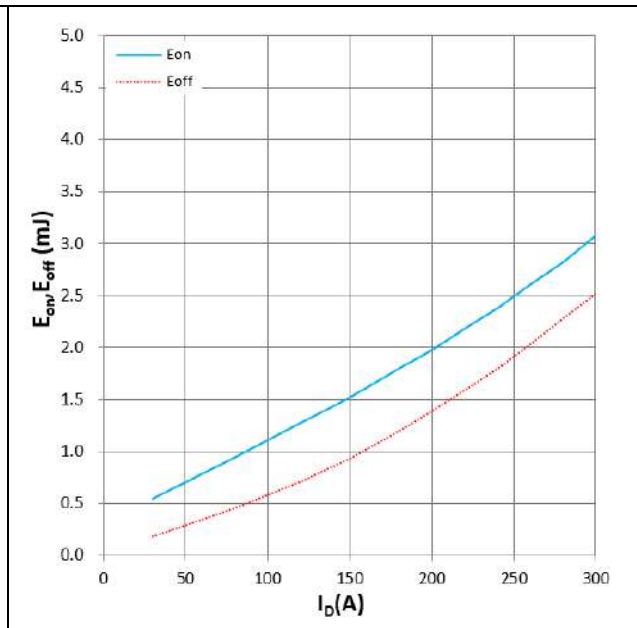


Figure 14.  $E_{on}$ ,  $E_{off}$  vs  $I_{DS}$   
 $T_j = 25^\circ\text{C}$ ,  $R_G = 3.3\Omega$ ,  $V_{GS} = +18\text{V}/-4\text{V}$

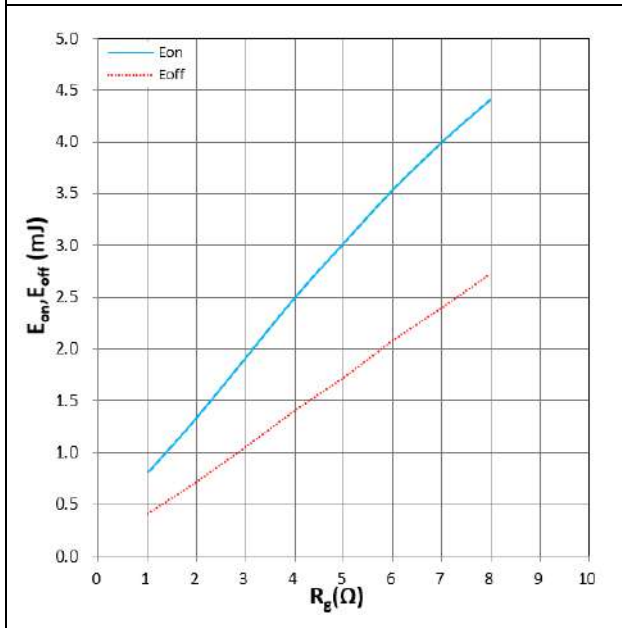


Figure 15.  $E_{on}$ ,  $E_{off}$  vs  $R_G$   
 $T_j = 150^\circ\text{C}$ ,  $I_D = 150\text{A}$ ,  $V_{GS} = +18\text{V}/-4\text{V}$

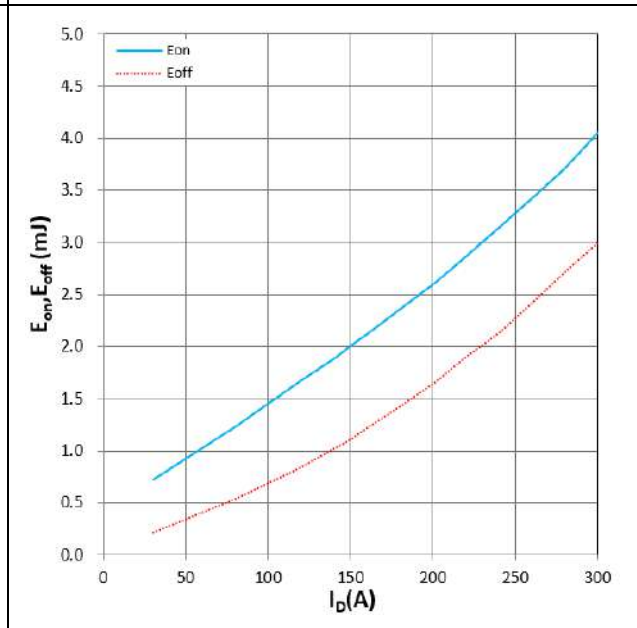


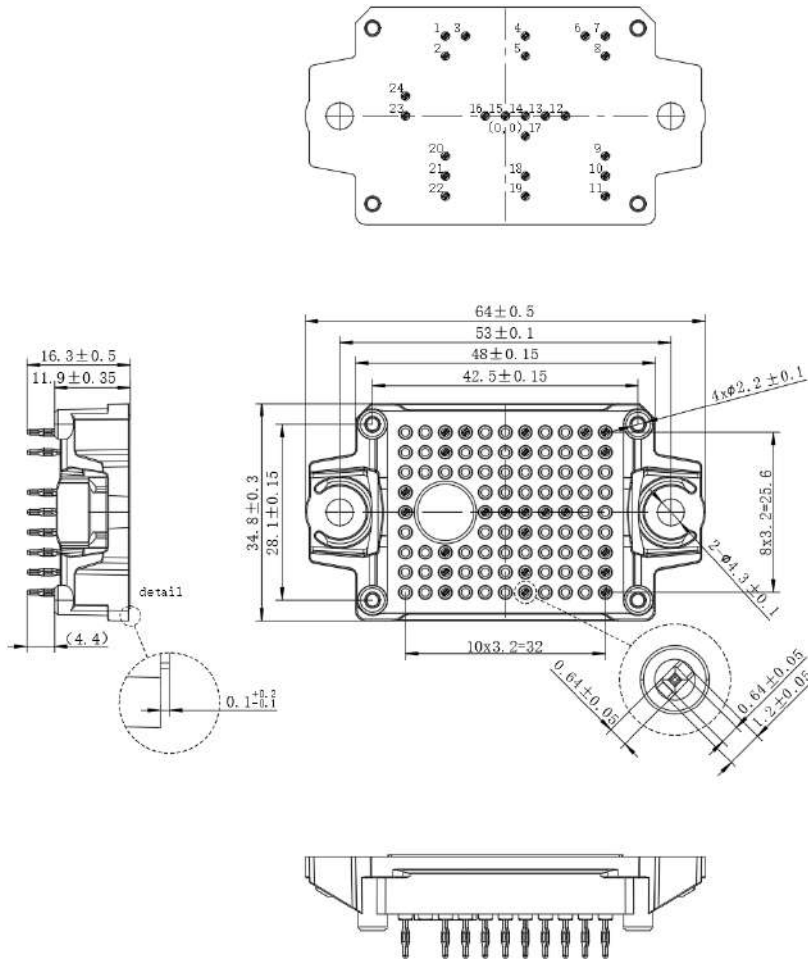
Figure 16.  $E_{on}$ ,  $E_{off}$  vs  $I_{DS}$   
 $T_j = 150^\circ\text{C}$ ,  $R_G = 3.3\Omega$ ,  $V_{GS} = +18\text{V}/-4\text{V}$



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### Package dimensions



Pin table		
Pin	X	Y
1	-9.6	12.8
2	-9.6	9.6
3	-6.4	12.8
4	3.2	12.8
5	3.2	9.6
6	12.8	12.8
7	16	12.8
8	16	9.6
9	16	-6.4
10	16	-9.6
11	16	-12.8
12	9.6	0
13	6.4	0
14	3.2	0
15	0	0
16	-3.2	0
17	3.2	-3.2
18	3.2	-9.6
19	3.2	-12.8
20	-9.6	-6.4
21	-9.6	-9.6
22	-9.6	-12.8
23	-16	0
24	-16	3.2

### IMPORTANT NOTICE

This product data sheet describes the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively under the terms and conditions of the supply agreement. There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances. For information on the types in question, please contact the sales staff responsible for you.

Changes to this product data sheet are reserved.

Please contact the sales staff ([sales@hiitio.com](mailto:sales@hiitio.com)) for further information on the product, technology, delivery terms, conditions and prices.

## Instruction note

Naming rules for power module product models (Industrial module)

Product Model							
	<b>HC</b>	<b>S</b>	<b>06</b>	<b>FF</b>	<b>120</b>	<b>E0</b>	<b>C1</b>
Hecheng Code							
Module type G : IGBT module D : FRD module S : SiC module H : Si/SiC hybrid							
On-state resistance (mΩ) 01~80							
Topology structure FZ : A switch unit    FF : Half bridge FS : Three phase    F4 : H Bridge F3L : Three level    DF : Boost Circuit FD : Braking Circuit FP : Rectification+Inverter+Control move AL : ANPC              CL : Chopper							
Voltage level (x10) (V)    650~2200							
Packaging form+features (A...Z)							
	A1: 34 mm	A2: 62 mm					
	B1: Easy 1B	B1A			B1B...		
	B2: Easy 2B...	B3: Easy 3B...					
	D1: Flow0	D2: Flow1			D3: Flow2		
	E0 : E0	E1: Econo 2...			E2: E2		
	E3: ED3	E4 : E4			E5 : ED3S		
	E6 : EPM2	E7 : EPM3			E8 : EconoPIM3		
	E9 : ED3H	F0 : F0			P2 : EPM2		
Feature :A: Special Code    Nil: Standard							

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